



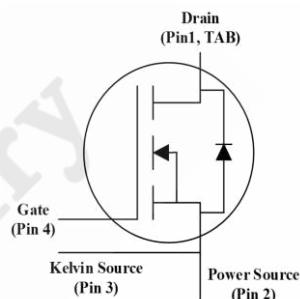
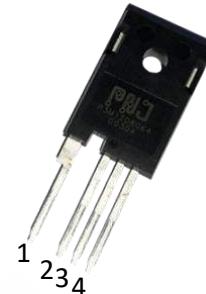
## P3M12160K4 SiC MOS N-Channel Enhancement Mode

$V_{RRM}$  = 1200 V  
 $I_D$  = 19 A  
 $I_D$  (100°C) = 13 A  
 $R_{DS(on)}$  = 160 mΩ

### SiC MOS P3M12160K4 N-Channel Enhancement Mode

#### Features

- Qualified to AEC-Q101
- High Blocking Voltage with Low On-Resistance
- High-Frequency Operation
- Ultra-Small  $Q_{gd}$
- 100% UIS tested



TO-247-4

Drain	1
Power Source	2
Kelvin Source	3
Gate	4



#### Application

- Solar Inverters
- EV Battery Chargers
- High Voltage DC/DC Converters
- Switch Mode Power Supplies

#### Order Information

Part number	Package	Marking
P3M12160K4	TO-247-4	P3M12160K4



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# P3M12160K4 SiC MOS

## N-Channel Enhancement Mode

### 1. Maximum Ratings

At  $T_J = 25^\circ\text{C}$ , unless specified otherwise

Parameter	Symbol	Value	Unit	Test Conditions
Drain - Source Voltage	$V_{DS\max}$	1200	V	$V_{GS} = 0\text{V}$ $I_D = 100\mu\text{A}$
Gate - Source Voltage (dynamic)	$V_{GS\max}$	-8 / +21	V	AC ( $f > 1\text{Hz}$ )
Gate - Source Voltage (static)	$V_{GSop}$	-3 / +15	V	Static
Continuous Drain Current	$I_D$	19	A	$V_{GS} = 15\text{V}$ $T_C = 25^\circ\text{C}$
		13		$V_{GS} = 15\text{V}$ $T_C = 100^\circ\text{C}$
Power Dissipation	$P_D$	110	W	
Operating Junction	$T_J$	-55 To +175	°C	
Storage Temperature	$T_{stg}$	-55 To +175	°C	
Solder Temperature	$T_L$	260	°C	
Mounting Torque	$M_d$	1 8.8	Nm lbf-in	M3 or 6-32 screw



## 2. Electrical Characteristics

At  $T_J = 25^\circ\text{C}$ , unless specified otherwise

Parameter	Symbol	Value			Unit	Test Conditions
		Min.	Typ.	Max.		
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	1200	/	/	V	$V_{GS} = 0\text{V}$ $I_D = 100\mu\text{A}$
Gate Threshold Voltage	$V_{GS(\text{th})}$	1.8	2.4	/	V	(tested after 30ms pulse at $V_{GS} = 15\text{V}$ ) $V_{DS} = V_{GS}$ $I_D = 2.5\text{mA}$ $T_J = 25^\circ\text{C}$
		/	1.6	/	V	$V_{DS} = V_{GS}$ $I_D = 2.5\text{mA}$ $T_J = 175^\circ\text{C}$
Zero Gate Voltage Drain Current	$I_{DSS}$	/	1.8	500	$\mu\text{A}$	$V_{GS} = 0\text{V}$ $V_{DS} = 1200\text{V}$
Gate-Source Leakage Current	$I_{GSS}$	/	20	250	nA	$V_{GS} = 15\text{V}$ $V_{DS} = 0\text{V}$
Drain-Source On-State Resistance	$R_{DS(\text{on})}$	/	160	192	$\text{m}\Omega$	$V_{GS} = 15\text{V}$ $I_D = 10\text{A}$ $T_J = 25^\circ\text{C}$
		/	208	/		$V_{GS} = 15\text{V}$ $I_D = 10\text{A}$ $T_J = 175^\circ\text{C}$
Transconductance	$g_{fs}$	/	5	/	S	$V_{DS} = 20\text{V}$ $I_{DS} = 10\text{A}$ $T_J = 25^\circ\text{C}$
		/	4.8	/		$V_{DS} = 20\text{V}$ $I_{DS} = 10\text{A}$ $T_J = 175^\circ\text{C}$



**P3M12160K4 SiC MOS**  
**N-Channel Enhancement Mode**

Parameter	Symbol	Value			Unit	Test Conditions
		Min.	Typ.	Max.		
Input Capacitance	$C_{iss}$	/	1016	/	pF	$V_{GS} = 0V$ $V_{DS} = 800V$ $f = 1MHz$ $V_{AC} = 25mV$
Output Capacitance	$C_{oss}$	/	36.8	/		
Reverse Transfer Capacitance	$C_{rss}$	/	3.2	/		
Coss Stored Energy	$E_{oss}$	/	26.5	/		
Gate to Source Charge	$Q_{gs}$	/	11.1	/		
Gate to Drain Charge	$Q_{gd}$	/	6.1	/		
Total Gate Charge	$Q_g$	/	27.3	/		

### 3. Reverse Diode Characteristics

At  $T_J = 25^\circ C$ , unless specified otherwise

Parameter	Symbol	Value		Unit	Test Conditions
		Typ.	Max.		
Diode Forward Voltage	$V_{SD}$	5.2	/	V	$V_{GS} = -3V$ $I_{SD} = 5A$ $T_J = 25^\circ C$
		4.8	/		
Continuous Diode Forward Current	$I_S$	13	/	A	$V_{GS} = -3V$



# P3M12160K4 SiC MOS N-Channel Enhancement Mode

## 4. Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction to Case	$R_{\theta JC}$	1.36	°C/W

## 5. Typical Performance

At  $T_J = 25^\circ\text{C}$ , unless specified otherwise

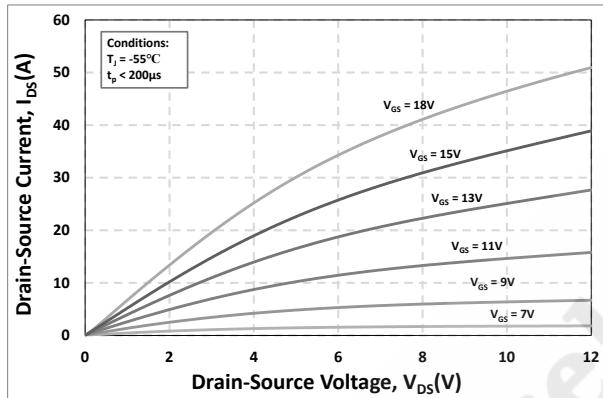


Figure 1. Output Characteristics  $T_J = -55^\circ\text{C}$

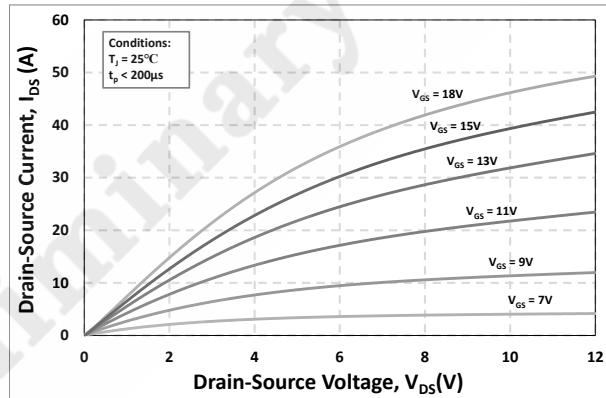


Figure 2. Output Characteristics  $T_J = 25^\circ\text{C}$

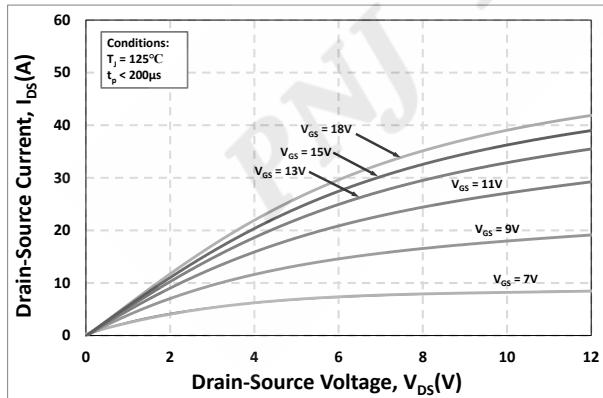


Figure 3. Output Characteristics  $T_J = 125^\circ\text{C}$

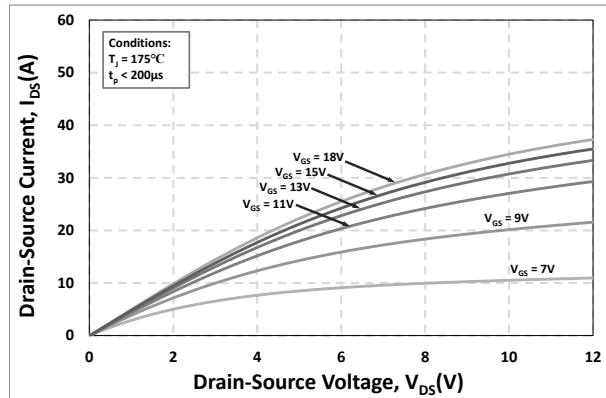


Figure 4. Output Characteristics  $T_J = 175^\circ\text{C}$



# P3M12160K4 SiC MOS N-Channel Enhancement Mode

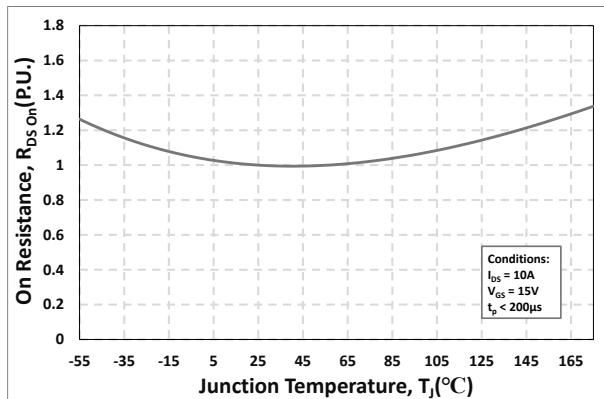


Figure 5. Normalized On-Resistance vs. Temperature

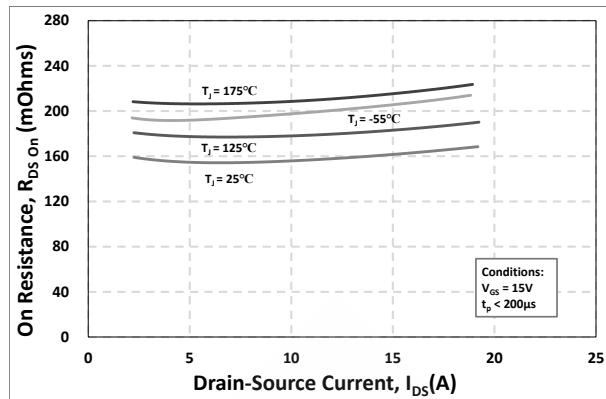


Figure 6. On-Resistance vs. Drain Current Various Temperatures

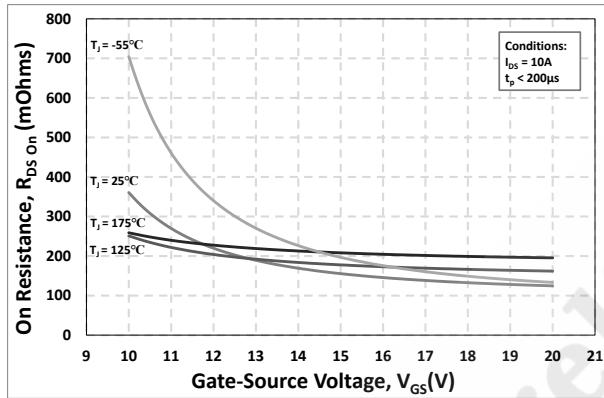


Figure 7. On-Resistance vs. Gate-Source Voltage

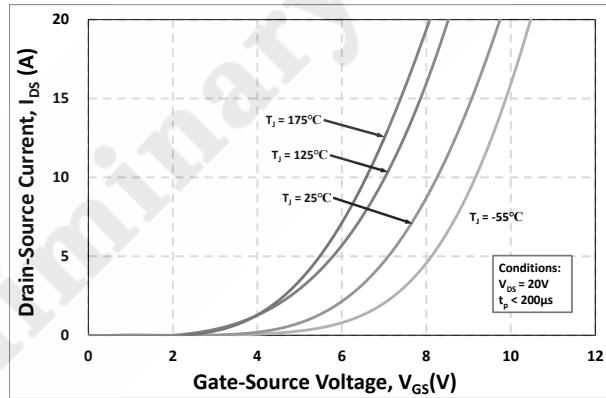


Figure 8. Transfer Characteristic for Various Junction Temperatures

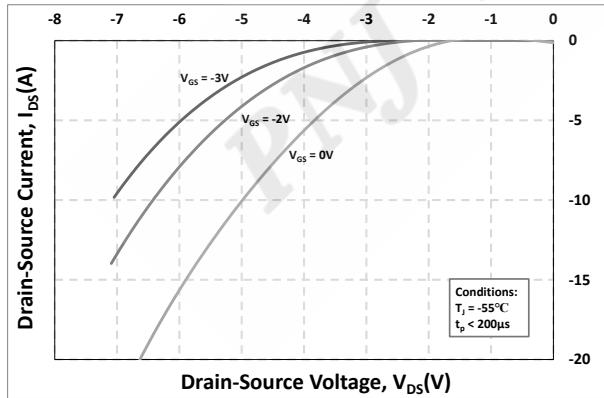


Figure 9. Body Diode Characteristic at  $-55^\circ\text{C}$

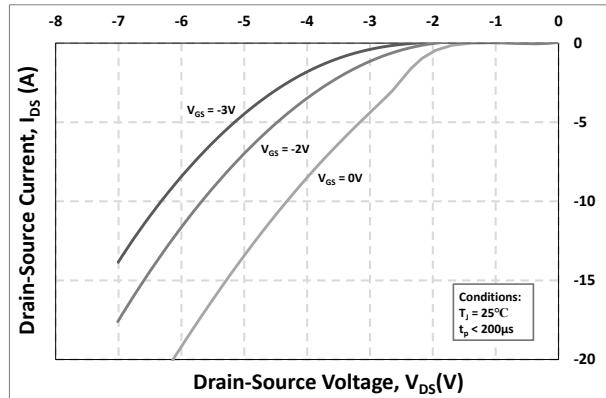
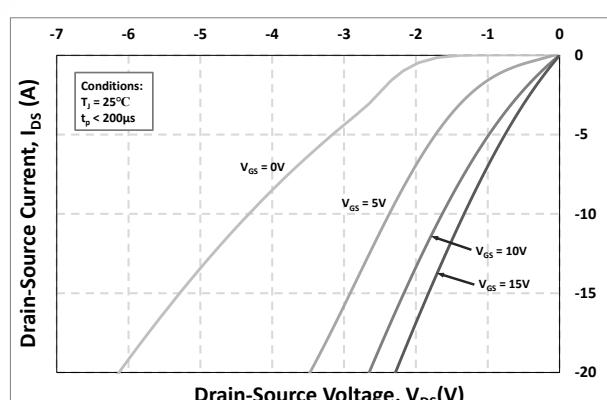
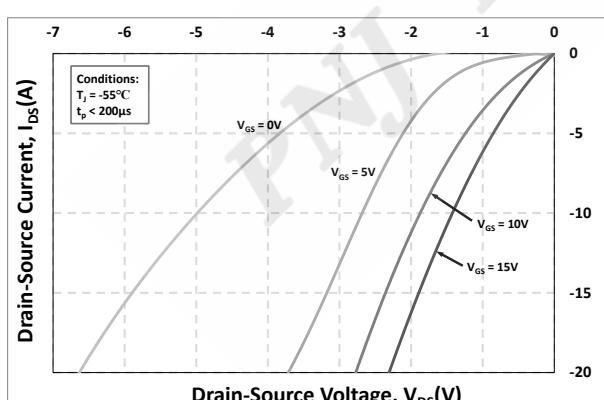
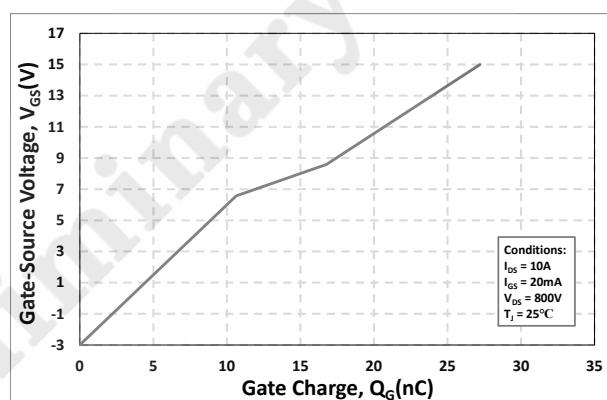
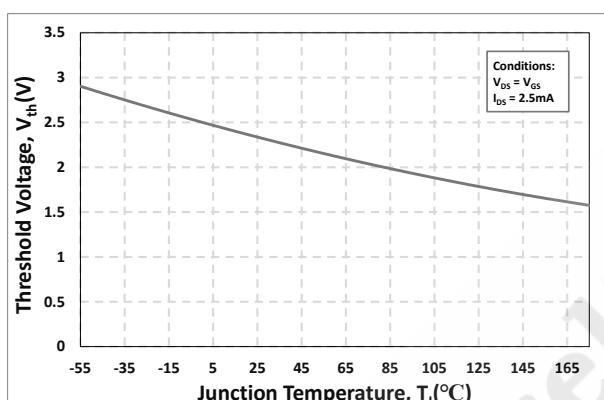
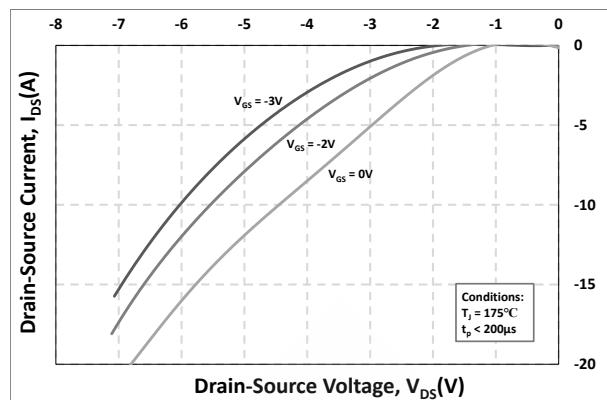
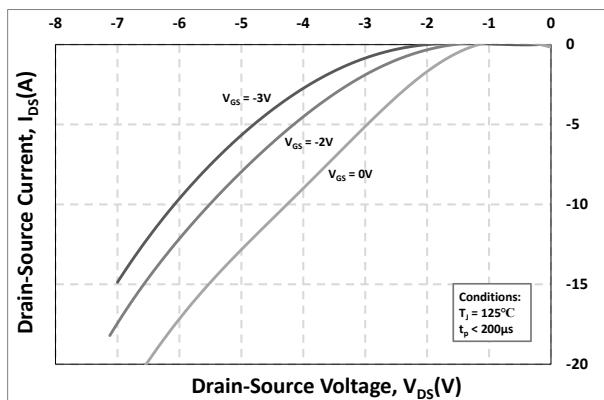


Figure 10. Body Diode Characteristic at  $25^\circ\text{C}$



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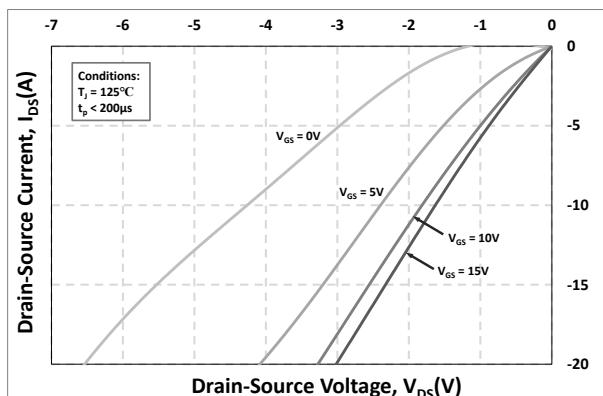


Figure 17. 3rd Quadrant Characteristic at  $125^\circ\text{C}$

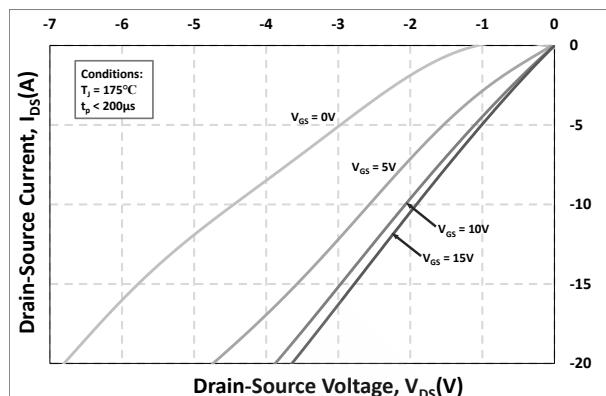


Figure 18. 3rd Quadrant Characteristic at  $175^\circ\text{C}$

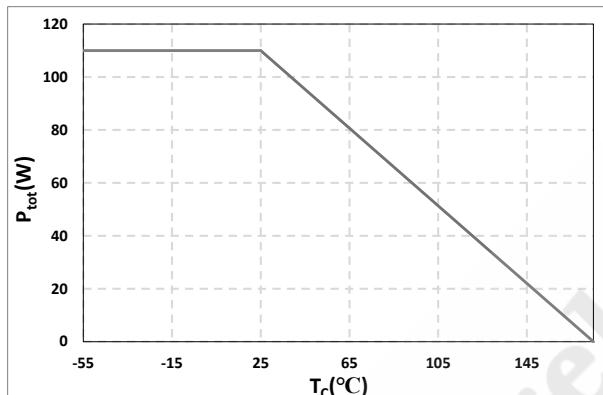


Figure 19. Maximum Power Dissipation Derating vs. Case Temperature

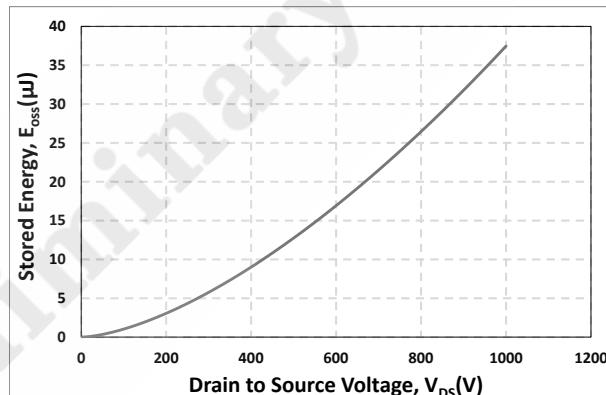


Figure 20. Output Capacitor Stored Energy

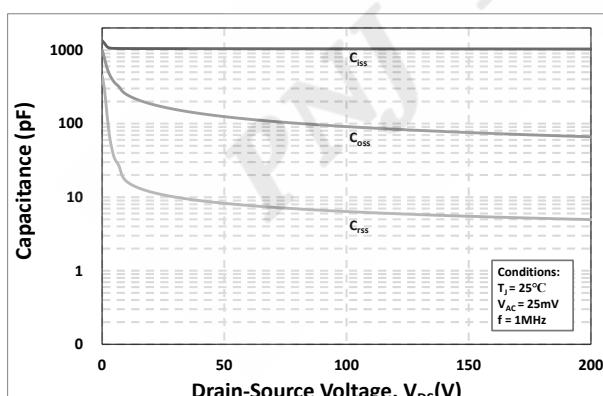


Figure 21. Capacitances vs. Drain-Source Voltage (0 - 200V)

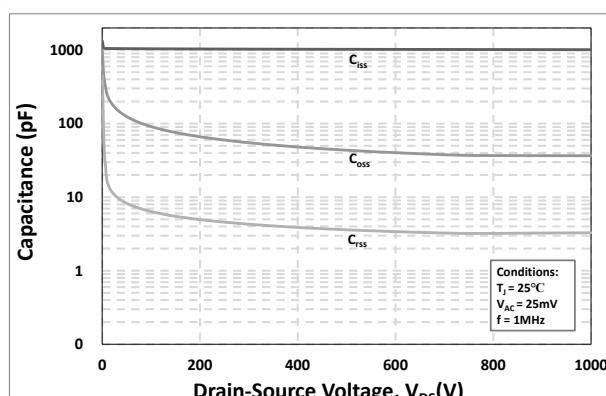


Figure 22. Capacitances vs. Drain-Source Voltage (0 - 1000V)



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## 6. Definitions

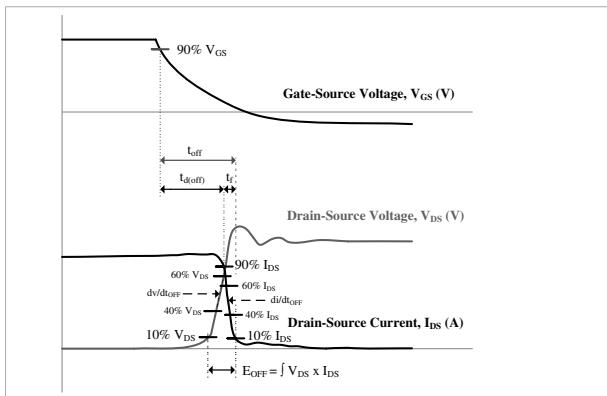


Figure 23. Turn-off Transient Definitions

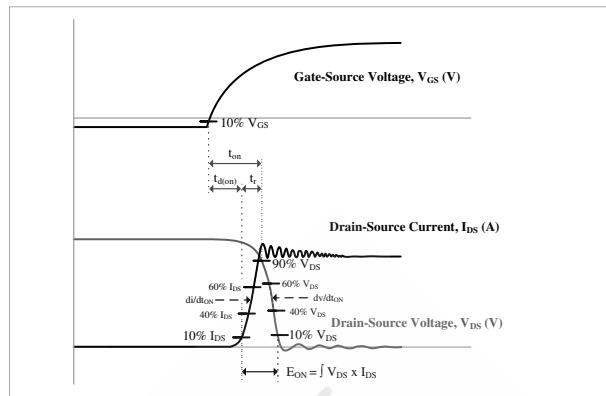


Figure 24. Turn-on Transient Definitions

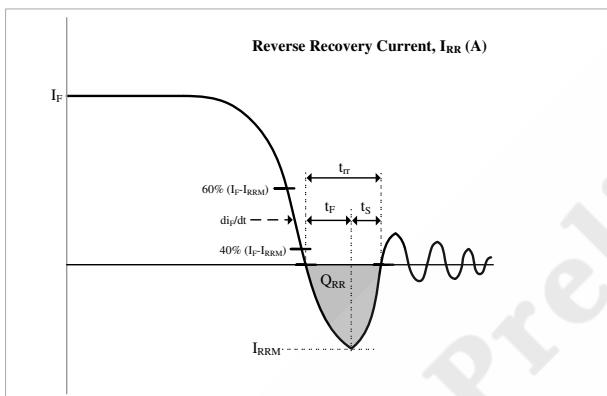


Figure 25. Reverse Recovery Definitions

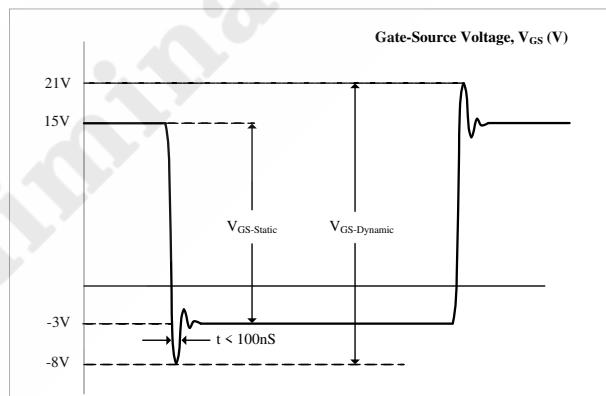
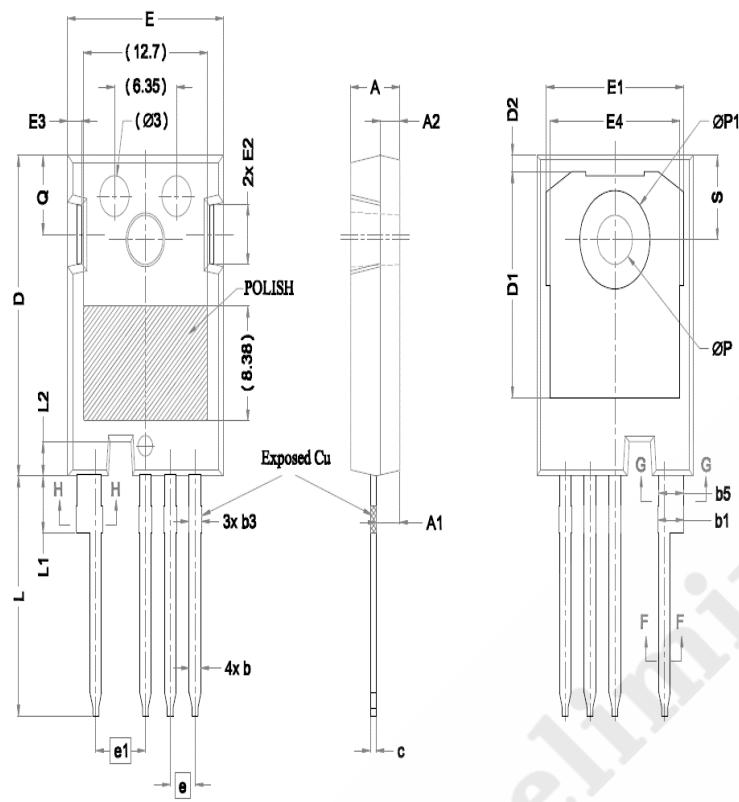


Figure 26. vgs Transient Definitions



# P3M12160K4 SiC MOS N-Channel Enhancement Mode

## 7. Package Outlines



Symbol	Dimensions		
	Min.	Nom.	Max.
A	4.83	5.02	5.21
A1	2.28	2.41	2.54
A2	1.91	2.00	2.16
b <sup>1</sup>	1.07	1.20	1.28
b	1.07	1.20	1.33
b1	2.39	2.67	2.94
b2	2.39	2.67	2.84
b3	1.07	1.30	1.60
b4	1.07	1.30	1.50
b5	2.39	2.53	2.69
b6	2.39	2.53	2.64
c	0.55	0.60	0.68
c1	0.55	0.60	0.65
D	22.30	23.45	23.80
D1	16.25	16.55	17.65
D2	0.95	1.19	1.25
E	15.75	15.94	16.13
E1	13.10	14.02	14.15
E2	3.60	1.10	5.10
E3	1.00	1.45	1.90
E4	12.38	13.26	13.43
e	2.54BSC		
e1	5.08BSC		
L	17.31	17.57	17.82
L1	3.97	4.19	4.37
L2	2.35	2.50	2.65
OP	3.51	3.61	3.65
OP	7.19 REF.		
Q	5.49	5.79	6.00
S	6.04	6.17	6.30

Drawing and Dimensions



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